

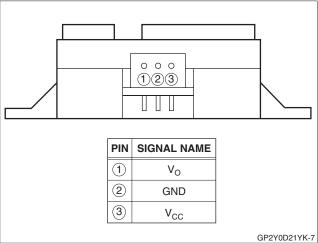
FEATURES

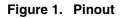
- Trigger point set at factory to 24°
- Digital output
- LED Pulse Cycle Duration: 32 ms
- Range: 10 to 80 cm
- Typical response time: 39 ms
- Typical start up delay: 46 ms
- Average current consumption: 30 mA
- Detection Area Diameter @ L = 80 cm: 12 cm

DESCRIPTION

The GP2Y0D21YK is a distance measuring sensor with integrated signal processing and digital output.







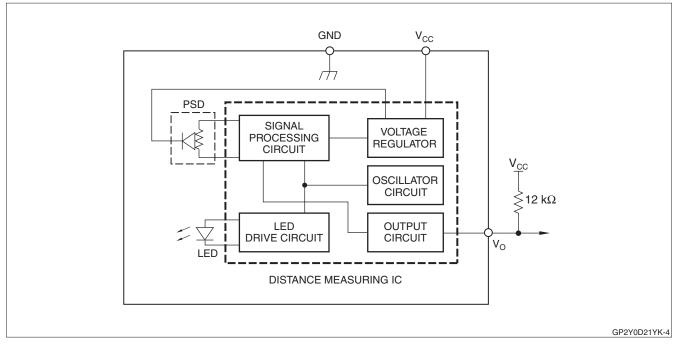


Figure 2. Block Diagram

ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings

Ta = 25° C, V_{CC} = 5 VDC

PARAMETER	SYMBOL	RATING	UNIT	REMARKS
Supply Voltage	V _{CC}	-0.3 to +7.0	V	
Output Terminal Voltage	V _O	-0.3 to (V _{CC} + 0.3)	V	Open collector output
Operating Temperature	Topr	-10 to +60	°C	
Storage Temperature	Tstg	-40 to +70	°C	

Operating Supply Voltage

PARAMETER	SYMBOL	RATING	UNIT	
Operating Supply Voltage	V _{CC}	4.5 to 5.5	V	

Electro-optical Characteristics

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT	NOTES
Measuring Distance Range	ΔL		10	_	80	cm	1, 3
Output Terminal Voltage	V _{OH}	Output voltage at HIGH level	V _{CC} - 0.3	_	_	V	1
	V _{OL}	Output voltage at LOW level	_	_	0.6	V	1
Output Distance Characteristics	Vo		21	24	27	cm	1, 2, 4
Average Supply Current	I _{CC}			30	40	mA	

NOTES:

1. Measurements made with Kodak R-27 Gray Card, using the white side, (90% reflectivity).

2. Set at factory for guaranteed measurement at L = 24 cm \pm 3 cm.

3. Measurement adjustment range.

4. Output switching has hysteresis. The distance specified by V_O is for switching from LOW to HIGH.

5. * L = Distance to reflective object.

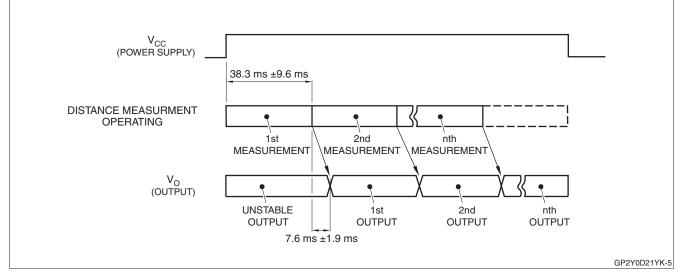


Figure 3. Timing Diagram

REALIABILITY

The reliability requirements of this device are listed in Table 1.

TEST ITEMS	TEST CONDITIONS	FAILURE JUDGEMENT CRITERIA	SAMPLES (n), DEFECTIVE (C)
Temperature Cycling	One cycle -40°C (30 min.) to +70°C in 30 minutes, repeated 25 times		n = 11, C = 0
High Temperature and High Humidity Storage	+40°C, 90% RH, 500h		n = 11, C = 0
High Temperature Storage	+70°C, 500h		n = 11, C = 0
Low Temperature Storage	-40°C, 500h	Initial × 0.8 > V _O	
Operational Life (High Temperature)	+60°C, V _{CC} = 5 V, 500h	$V_0 > Initial \times 1.2$	n = 11, C = 0
Mechanical Shock	100 m/s², 6.0 ms 3 times/±X, ±Y, ±Z direction		n = 6, C = 0
Variable Frequency Vibration	10-to-55-to-10 Hz in 1 minute Amplitude: 1.5 mm 2h in each X, Y, Z direction		n = 6, C = 0

NOTES:

1. Test conditions are according to Electro-optical Characteristics, shown on page 2.

2. At completion of the test, allow device to remain at nominal room temperature and humidity (non-condensing) for two hours.

3. Confidence level: 90%, Lot Tolerance Percent Defect (LTPD): 20%/40%.

MANUFACTURER'S INSPECTION

Inspection Lot

Inspection shall be carried out per each delivery lot.

Inspection Method

A single sampling plan, normal inspection level II based on ISO 2859 shall be adopted.

Table 2. Quality Level

DEFECT	INSPECTION ITEM and TEST METHOD		
Major Defect	Electro-optical characteristics defect	0.4	
Minor Defect	Defect to appearance or dimensions (crack, split, chip, scratch, stain)*	1.0	

NOTE: *Any one of these that affects the Electro-optical Characteristics shall be considered a defect.

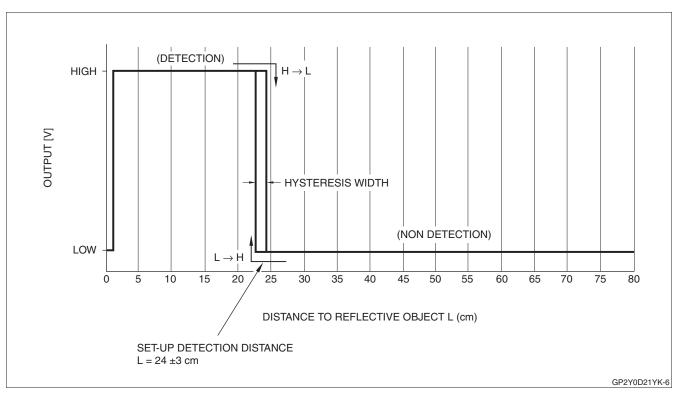
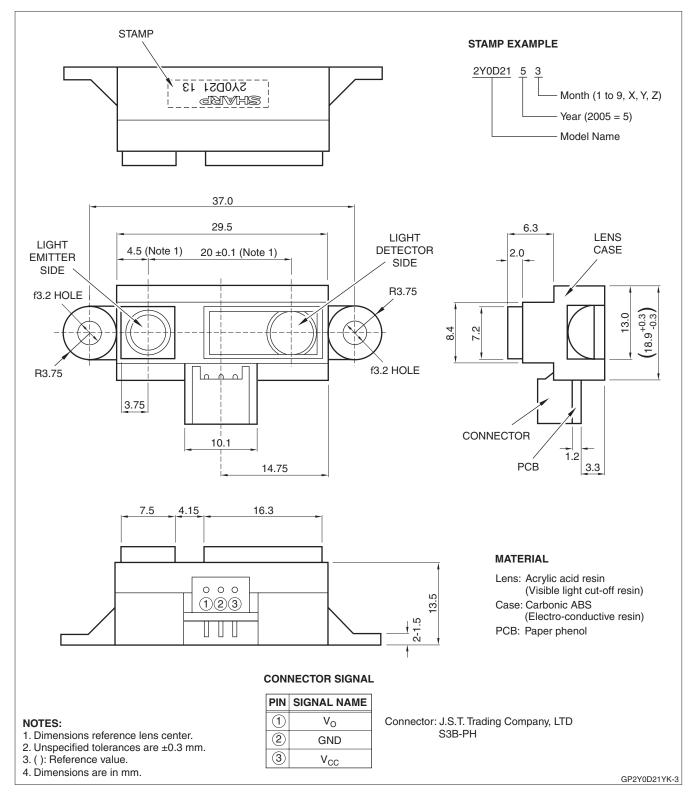
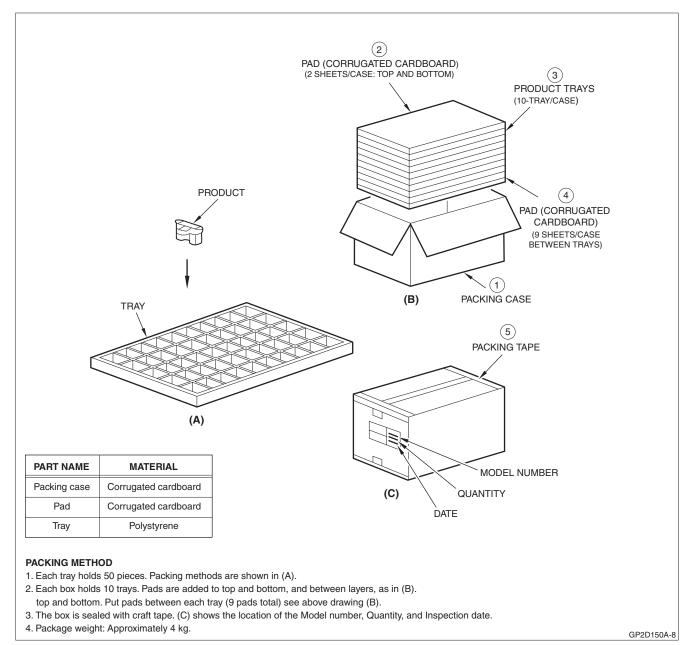


Figure 4. GP2Y0D21YK Example of Output Distance Characteristics

PACKAGE SPECIFICATIONS



PACKING SPECIFICATION



NOTES

- Keep the sensor lens clean. Dust, water, oil, and other contaminants can deteriorate the characteristics of this device. Applications should be designed to eliminate sources of lens contamination.
- When using a protective cover over the emitter and detector, ensure the cover efficiently transmits light throughout the wavelength range of the LED ($\lambda = 850 \text{ nm} \pm 70 \text{ nm}$). Both sides of the protective cover should be highly polished. Use of a protective cover may decrease the effective distance over which the sensor operates. Ensure that any cover does not negatively affect the operation over the intended application range.
- Objects in proximity to the sensor may cause reflections that can affect the operation of the sensor.
- Sources of high ambient light (the sun or strong artificial light) may affect measurement. For best results, the application should be designed to prevent interference from direct sunlight or artificial light.

- Using the sensor with a mirror can induce measurement errors. Often, changing the incident angle on the mirror can correct this problem.
- If a prominent boundary line exists in the surface being measured, it should be aligned vertically to avoid measurement error. See Figure 5 for further details.
- When measuring the distance to objects in motion, align the sensor so that the motion is in the horizontal direction instead of vertical. Figure 6 illustrates the preferred alignment.
- A 10 μF (or larger) bypass capacitor between V_{CC} and GND near the sensor is recommended.
- To clean the sensor, use a dry cloth. Use of any liquid to clean the device may result in decreased sensitivity or complete failure.
- Excessive mechanical stress can damage the internal sensor or lens.

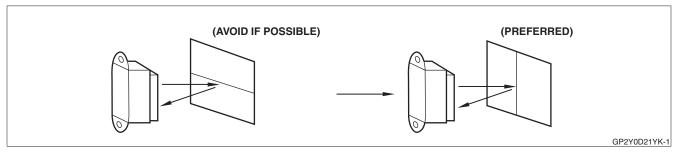


Figure 5. Proper Alignment to Surface Being Measured

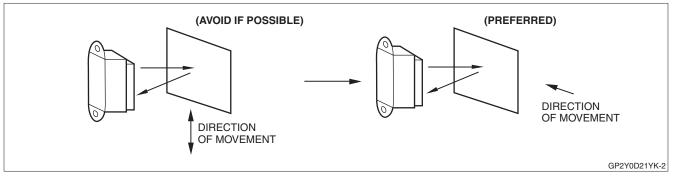


Figure 6. Proper Alignment to Moving Surfaces

NOTICE

The circuit application examples in this publication are provided to explain representative applications of SHARP devices and are not intended to guarantee any circuit design or license any intellectual property right. SHARP takes no responsibility for any problems related to any intellectual property right of a third party resulting from the use of SHARP devices.

SHARP reserves the right to make changes in the specifications, characteristics, data, materials, structures and other contents described herein at any time without notice in order to improve design or reliability.

Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device. Manufacturing locations are also subject to change without notice.

In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that occur in equipment using any SHARP devices shown in catalogs, data books, etc.

The devices listed in this publication are designed for standard applications for use in general electronic equipment. SHARP's devices shall not be used for or in connection with equipment that requires an extremely high level of reliability, such as military and aerospace applications, telecommunication equipment (trunk lines), nuclear power control equipment and medical or other life support equipment (e.g. Scuba). SHARP takes no responsibility for damage caused by improper use of device, which does not meet the conditions for use specified in the relevant specification sheet.

If the SHARP devices listed in the publication fall within the scope of strategic products described in the Foreign Exchange and Foreign Trade Law of Japan, it is necessary to obtain approval to export such SHARP devices.

This publication is the proprietary product of SHARP and is copyrighted, with all rights reserved. Under the copyright laws, no part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical for any purpose, in whole or in part, without the express written permission of SHARP. Express written permission is also required before any use of this publication may be made by a third party.

Contact and consult with a SHARP representative if there are any questions about the contents of this publication.

SHARP

SHARP CORPORATION SALES & MARKETING GROUP ELECTRONIC COMPONENTS & DEVICES 22-22 NAGAIKE-CHO, ABENO-KU, OSAKA 545-8522, JAPAN PHONE: (81) 6-6621-1221 FAX: (81) 6117-725300, 6117-725301, 6117-725302 http://sharp-world.com/products/device

Specifications are subject to change without notice.

U.S.A.

SHARP MICROELECTRONICS OF THE AMERICAS

North American Head Office

5700 North West Pacific Rim Boulevard Camas,Washington 98607 USA PHONE: (1)360-834-2500 FAX: (1)360-834-8903 http://www.sharpsma.com

Western Area

1980 Zanker Road, San Jose, CA 95112 PHONE: (1)408-436-4900 FAX: (1)408-436-0924

5901 Bolsa Ave. Huntington Beach, CA 92647-2053 PHONE: (1)714-903-4600 FAX: (1)714-903-0295

6390 Greenwich Drive, S uite 175 San Diego, CA 92122 PHONE: (1)858-597-0982 FAX: (1)858-597-8701

Central Area

85 W. Algonquin Road, Suite 280 Arlington Heights, IL 60005 PHONE: (1)847-258-2750 FAX: (1)847-439-2479

6303 Commerce Drive, Suite 175 Irving, TX 75063 PHONE: (1)972-582-1710 FAX: (1)972-580-7537

8911 Capitol of Texas Hwy. Suite 3130 Austin, TX 78759 PHONE: (1)512-349-7262 FAX: (1)512-349-7002

20333 State Hwy. 249, Suite 200 Houston, TX 77070 PHONE: (1)281-378-1520 FAX: (1)281-378-1521

W129 S 9647 Tony Lema Lane Muskego, WI 53150 PHONE: (1)414-529-9568 FAX: (1)414-529-9569

3001 West Big Beaver Road, Suite 722 Troy, ML 48084 PHONE: (1)248-458-1527 FAX: (1)248-458-6255

Eastern Area

1070 N. Kimbles Road, Yardley, PA 19067 PHONE: (1)215-321-5530 FAX: (1)215-321-5534

200 Wheeler Rd., Burlington, MA 01803 PHONE: (1)781-270-7979; (1)781-229-5100 FAX: (1)781-229-9117

8000 Regency Parkway, Suite 280 Cary, NC 27511 PHONE: (1)919-460-0695 FAX: (1)919-460-0795

2321 Sidney St. Pittsburgh, PA 15203 PHONE: (1)412-381-1191 FAX: (1)412-381-1192

4875 North Federal Highway, Third Floor Ft. Lauderlade, FL 33318 PHONE: (1)954-267-8883 FAX: (1)954-267-0254

Countries and Areas

EUROPE

SHARP MICROELECTRONICS EUROPE A division of Sharp Electronics (Europe) GmbH

Head Office

Sonninstrasse 3, 20097, Hamburg, Germany PHONE: (49)180-5073507 FAX: (49)40-2376-2232 http://www.sharpsme.com/

Germany

SME München Office Fuerstenriederstrasse 5, 80687 München, Germany PHONE: (49)89-5468420 FAX: (49)89-54 684250

France

SME Paris Office 1 Rue Raoul Follereau Bussy Saint Georges 77608 Marne la Vallee Cedex 3 PHONE: (33)1 6476 22 22 FAX: (33)1 6476 22 23

Italy

SME Milano Office Centro Direzionale Colleoni Palazzo Taurus Ingresso 2 20041 Agrate Brianza, Milano, Italy PHONE: (390)39-68 99 946 FAX: (390)39-68 99 948

U.K .

SME London Office Centennial Court, Easthampstead Road, Bracknell, Berkshire R G12 1YQ, United Kingdom PHONE: (44)1344-86 99 22 FAX: (44)1344-36 09 03

Ireland

SME Dublin Office First Floor, Block 1, St. Johns Court, Santry, Dublin 9, Ireland PHONE: (353)1-842 87 05 FAX: (353)1-842 84 55

ASIA

SHARP ELECTRONICS (SHANGHAI) CO., LTD. Microelectronics Sales & Marketing Division 16F, King Tower, 28 Xin Jin Qiao Road, Pudong DIST, Shanghai 201206 P.R. China PHONE: (86)21-5854-7710/21-5834-6056 FAX: (86)21-5854-4340/21-5834-6057

Distributed By

Registered Address

No. 11, De Bao Road, Xin Development BLDG 46 Wai Gao Qiao Free Trade Zone, Shanghai 200131, P.R. China

Beijing Office

Room 1062, Beijing Jing An Center No. 8 East Bei San Huan Road, Chao Yang DIST, Beijing 100028 P.R. China PHONE: (86) 10-6466-7543/10-6466-6561 FAX: (86) 10-6468-8920 http://sharp-world.com/products/devicechina/ index.html

SHARP-ROXY (HONG KONG) LTD. Device Sales Division, 17/F, Admiralty Centre, Tower 1, 18 Harcourt Road, Hong Kong PHONE: (852)28229311 FAX: (852)28660779 http://www.sharp.com.hk

Shenzhen Representative Office

Room 13B1, Tower C, Electronics Science & Technology Building, Shen Nan Zhong Road, Shenzhen, P.R. China PHONE: (86)755-83273731 FAX: (86)755-83273735

SHARP ELECTRONIC COMPONENTS

(TAIWAN) CORPORATION 8F-A, No. 16, Sec. 4, Nanking E. R d., Taipei, Taiwan PHONE: (886)2-2577-7341 FAX: (886)2-2577-7326/2-2577-7328

SHARP ELECTRONICS (SINGAPORE) PTE ., LTD. 396 Alexandra Road #07-00 BP Tower Singapore 119954 PHONE: (65) 62713566 FAX: (65) 62713855 http://www.sesl-sharp.com

SHARP MICROELECTRONICS TECHNOLOGY (M) SDN BHD. Suite E 408, 4th Floor, East Tower, Wisma Consplant 1, No. 2 J In. SS 16/4, Subng Jaya, 47500, Selangor Darul Ehsan, Malaysia PHONE: (60) 3-5637-8964 FAX: (60) 3-5638-4029

SHARP ELECTRONIC COMPONENTS (KOREA) CORPORATION RM 501 iLsin B/D. 541, Dohwa-dong, Mapo-ku, Seoul, Korea, 121-701 PHONE: (82)2-711-5813 ~ 8 FAX: (82)2-711-5819